

POLISHING APPARATUS

ABSTRACT OF THE DISCLOSURE

A polishing apparatus includes a polishing unit having a spindle having an axial bore defined therein, a housing by which the spindle is rotatably supported, a polishing pad mounted on an end of the spindle and having an opening defined therein that is held in fluid communication with the axial bore, a slurry supply pipe inserted in the axial bore in the spindle and having a supply port supplying a slurry to the workpiece held on the chuck table and an inlet port remote from the supply port, introducing the slurry into the slurry supply pipe, a slurry introducing unit connected to the inlet port of the slurry supply pipe, introducing the slurry into the inlet port, and a cleaning water introducing unit connected to the inlet port of the slurry supply pipe, introducing cleaning water into the inlet port.

[Figure 2]